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1 [Circuit design and modeling: Maximum effective distance of on-chip decoupling](#)



[capacitors in power distribution grids](#)

 Mikhail Popovich, Eby G. Friedman, Michael Sotman, Avinoam Kolodny, Radu M. Secareanu
 April 2006 **Proceedings of the 16th ACM Great Lakes symposium on VLSI GLSVLSI '06**

Publisher: ACM Press

 Full text available: pdf(524.44 KB) Additional Information: [full citation](#), [abstract](#), [references](#), [index terms](#)

Decoupling capacitors are widely used to reduce power supply noise. On-chip decoupling capacitors have traditionally been allocated into the available white space on a die. The efficacy of on-chip decoupling capacitors depends upon the impedance of the power/ground lines connecting the capacitors to the current loads and power supplies. A maximum effective radius exists for each on-chip decoupling capacitor. Beyond this effective distance, a decoupling capacitor is completely ineffective. Two ef ...

Keywords: decoupling capacitors, power distribution grids, power distribution systems

2 [Power, buffering and open source: Effects of on-chip inductance on power](#)



[distribution grid](#)

Atsushi Muramatsu, Masanori Hashimoto, Hidetoshi Onodera

 April 2005 **Proceedings of the 2005 international symposium on Physical design ISPD '05**

Publisher: ACM Press

 Full text available: pdf(362.07 KB) Additional Information: [full citation](#), [abstract](#), [references](#), [index terms](#)

With increase of clock frequency, on-chip wire inductance starts to play an important role in power/ground distribution analysis, although it has not been considered so far. We perform a case study work that evaluates relation between decoupling capacitance position and noise suppression effect, and we reveal that placing decoupling capacitance close to current load is necessary for noise reduction. We experimentally show that impact of on-chip inductance becomes small when on-chip decoupling ca ...

Keywords: decoupling capacitance, on-chip inductance, power distribution network, power supply noise

3 [Power supply noise analysis methodology for deep-submicron VLSI chip design](#)



Howard H. Chen, David D. Ling



June 1997 **Proceedings of the 34th annual conference on Design automation DAC '97**

Publisher: ACM Press

Full text available: [pdf\(237.07 KB\)](#) Additional Information: [full citation](#), [abstract](#), [references](#), [citations](#), [index terms](#)



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This paper describes a new design methodology to analyze the on-chip power supply noise for high-performance microprocessors. Based on an integrated package-level and chip-level power bus model, and a simulated switching circuit model for each functional block, this methodology offers the most complete and accurate analysis of Vdd distribution for the entire chip. The analysis results not only provide designers with the inductive ΔI noise and the resistive IR drop data at the same time, but also allow d ...

4 Power-driven Design of Router Microarchitectures in On-chip Networks

Hangsheng Wang, Li-Shiuan Peh, Sharad Malik

December 2003 **Proceedings of the 36th annual IEEE/ACM International Symposium on Microarchitecture**

Publisher: IEEE Computer Society

Full text available: [pdf\(255.15 KB\)](#) Additional Information: [full citation](#), [abstract](#), [citations](#), [index terms](#)

As demand for bandwidth increases in systems-on-a-chip and chip multiprocessors, networks are fast replacing buses and dedicated wires as the pervasive interconnect fabric for on-chip communication. The tight delay requirements faced by on-chip networks have resulted in prior microarchitectures being largely performance-driven. While performance is a critical metric, on-chip networks are also extremely power-constrained. In this paper, we investigate on-chip network microarchitectures from a power-drive ...

5 Energy aware design: Power protocol: reducing power dissipation on off-chip data buses

K. Basu, A. Choudhary, J. Pisharath, M. Kandemir

November 2002 **Proceedings of the 35th annual ACM/IEEE international symposium on Microarchitecture**

Publisher: IEEE Computer Society Press

Full text available: [pdf\(1.18 MB\)](#) Additional Information: [full citation](#), [abstract](#), [references](#), [citations](#), [index terms](#)

[Publisher Site](#)

Power consumption is becoming increasingly important for both embedded and high-performance systems. Off-chip data buses can be a major power consumer. In this paper, we present a strategy called "power protocol" that tries to reduce the dynamic power dissipation on off-chip data buses. To accomplish this, our strategy reduces the number of bus lines that need to be activated for data transfer by employing a small cache (called "value cache") at each side of the off-chip data bus. These value cac ...

6 Low power memory system: System level power-performance trade-offs in embedded systems using voltage and frequency scaling of off-chip buses and memory



Kiran Puttaswamy, Kyu-Won Choi, Jun Cheol Park, Vincent J. Mooney, Abhijit Chatterjee, Peeter Ellervee

October 2002 **Proceedings of the 15th international symposium on System Synthesis**

Publisher: ACM Press

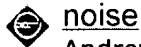
Full text available: [pdf\(84.16 KB\)](#) Additional Information: [full citation](#), [abstract](#), [references](#), [citations](#), [index terms](#)

In embedded systems, off-chip buses and memory (i.e., L2 memory as opposed to the L1 memory which is usually on-chip cache) consume significant power, often more than the processor itself. In this paper, for the case of an embedded system with one processor chip and one memory chip, we propose frequency and voltage scaling of the off-chip

buses and the memory chip and use a known micro-architectural enhancement called a store buffer to reduce the resulting impact on execution time. Our benchmark ...

Keywords: design space, embedded systems, power-performance trade-offs, voltage/frequency scaling

7 Power Grid and Signal Integrity Analysis: Scaling trends of on-chip Power distribution



noise

Andrey V. Mezhiba, Eby G. Friedman

April 2002 **Proceedings of the 2002 international workshop on System-level interconnect prediction**

Publisher: ACM Press

Full text available: pdf(110.79 KB) Additional Information: [full citation](#), [abstract](#), [references](#), [citations](#), [index terms](#)

The design of power distribution networks in high performance integrated circuits has become significantly more challenging with recent advances in process technology. As on-chip currents exceed tens of amperes and circuit clock periods are reduced well below a nanosecond, the signal integrity of the on-chip power supply has become a primary concern in integrated circuit design. The existing work on power distribution noise scaling is reviewed and extended to include the scaling of the inductanc ...

Keywords: power distribution, power supply noise, technology scaling

8 System design methodology: Replacing global wires with an on-chip network: a



power analysis

Seongmoo Heo, Krste Asanović

August 2005 **Proceedings of the 2005 international symposium on Low power electronics and design ISLPED '05**

Publisher: ACM Press

Full text available: pdf(250.91 KB) Additional Information: [full citation](#), [abstract](#), [references](#), [index terms](#)

This paper explores the power implications of replacing global chip wires with an on-chip network. We optimize network links by varying repeater spacing, link pipelining, and voltage scaling, to significantly reduce the energy to send a bit across chip. We develop an analytic model of large chip designs with an on-chip two-dimensional mesh network and estimate the power savings possible in a 70 nm process for two different design points: a circuit-switched ASIC or FPGA design, and a dynamic pack ...

Keywords: on-chip network power model, pipelining, router, tile size, tiled architecture, wire power model

9 Leakage estimation: Full chip leakage estimation considering power supply and



temperature variations

Haihua Su, Frank Liu, Anirudh Devgan, Emrah Acar, Sani Nassif

August 2003 **Proceedings of the 2003 international symposium on Low power electronics and design**

Publisher: ACM Press


Full text available: pdf(1.15 MB) Additional Information: [full citation](#), [abstract](#), [references](#), [citations](#), [index terms](#)

Leakage power is emerging as a key design challenge in current and future CMOS designs. Since leakage is critically dependent on operating temperature and power supply, we present a full chip leakage estimation technique which accurately accounts for power

supply and temperature variations. State of the art techniques are used to compute the thermal and power supply profile of the entire chip. Closed-form models are presented which relate leakage to temperature and VDD variations. These models c ...

Keywords: leakage power, supply voltage variation, thermal analysis

10 Managing power and performance for System-on-Chip designs using Voltage Islands

 David E. Lackey, Paul S. Zuchowski, Thomas R. Bednar, Douglas W. Stout, Scott W. Gould, John M. Cohn


November 2002 **Proceedings of the 2002 IEEE/ACM international conference on Computer-aided design**

Publisher: ACM Press

Full text available:  [pdf\(96.51 KB\)](#) Additional Information: [full citation](#), [abstract](#), [references](#), [citations](#), [index terms](#)

This paper discusses Voltage Islands, a system architecture and chip implementation methodology, that can be used to dramatically reduce active and static power consumption for System-on-Chip (SoC) designs. As technology scales for increased circuit density and performance, the need to reduce power consumption increases in significance as designers strive to utilize the advancing silicon capabilities. The consumer product market further drives the need to minimize chip power consumption. Effectiv ...

11 Low power SOC's and NOCs: High-level power analysis for on-chip networks

 Noel Eisley, Li-Shiuan Peh

September 2004 **Proceedings of the 2004 international conference on Compilers, architecture, and synthesis for embedded systems**

Publisher: ACM Press

Full text available:  [pdf\(353.56 KB\)](#) Additional Information: [full citation](#), [abstract](#), [references](#), [index terms](#)

As on-chip networks become prevalent in multiprocessor systems-on-a-chip and multi-core processors, they will be an integral part of the design flow of such systems. With power increasingly the primary constraint in chips, the tool chain in systems design, from simulation infrastructures to compilers and synthesis frameworks, needs to take network power into account, motivating the need for early-stage communication power analysis. While there has been substantial research in network performance ...

Keywords: link utilization, power analysis, simulation, systems-on-a-chip (SoC)

12 Poster Session 1: FIFO power optimization for on-chip networks

 Sudarshan Banerjee, Nikil Dutt

April 2004 **Proceedings of the 14th ACM Great Lakes symposium on VLSI**

Publisher: ACM Press

Full text available:  [pdf\(105.29 KB\)](#) Additional Information: [full citation](#), [abstract](#), [references](#), [index terms](#)

As the design community moves towards architecting multiprocessor systems-on-chip (MPSoC), it is widely believed that an on-chip interconnection network is potentially the best candidate to satisfy the high aggregate throughput needed by dozens of IP blocks. In this context, power (energy) estimation and reduction techniques for switches and links, the core components of an interconnection network, gain added significance. FIFO buffers are a key component of a majority of network switches - buff ...

Keywords: FIFO, low power design, on-chip networks, shared memory, switches, wide flits

13 An experimental system for power/timing optimization of LSI chips

B. J. Agule, J. D. Lesser, A. E. Ruehli, P. K. Wolff

January 1977 **Proceedings of the 14th conference on Design automation****Publisher:** IEEE PressFull text available: [pdf\(423.02 KB\)](#) Additional Information: [full citation](#), [abstract](#), [references](#), [citations](#), [index terms](#)

An experimental system of programs is described which places logic gates on a chip, globally wires the gates and then optimizes the power required to drive them. Further power reductions are realized by using power-oriented placement improvement techniques. A companion paper describes how the optimization is accomplished by using the timing requirements of the chip as constraints and assigning delays to the logic gates so that these constraints are met and the power is minimized.

14 Power distribution issues: Macro-modeling concepts for the chip electrical interface

Brian W. Amick, Claude R. Gauthier, Dean Liu

June 2002 **Proceedings of the 39th conference on Design automation****Publisher:** ACM PressFull text available: [pdf\(515.95 KB\)](#) Additional Information: [full citation](#), [abstract](#), [references](#), [index terms](#)

The power delivery network is made up of passive elements in the distribution network, as well as the active transistor loads. A chip typically has three types of power supplies that require attention: core, I/O, and analog. Core circuits consist of digital circuits and have the largest current demand. In addition to all of the system issues/models for the core, modeling the I/O subsystem has the additional requirement of modeling return paths and discontinuities. The analog circuits present yet ...

Keywords: VLSI power distribution, analog and I/O power delivery, high speed microprocessor design, inductance

15 Clock, power grid and thermal analysis and optimization: Fast computation of the temperature distribution in VLSI chips using the discrete cosine transform and tablelook-up

Yong Zhan, Sachin S. Sapatnekar

January 2005 **Proceedings of the 2005 conference on Asia South Pacific design automation ASP-DAC '05****Publisher:** ACM PressFull text available: [pdf\(1.25 MB\)](#) Additional Information: [full citation](#), [abstract](#), [references](#)

Temperature-related effects are critical in determining both the performance and reliability of VLSI circuits. Accurate and efficient estimation of the temperature distribution corresponding to a specific circuit layout is indispensable in physical design automation tools. In this paper, we propose a highly accurate fast algorithm for computing the on-chip temperature distribution due to power sources located on the top surface of the chip. The method is a combination of several computational te ...

16 Power-performance considerations of parallel computing on chip multiprocessors

Jian Li, José F. Martínez

December 2005 **ACM Transactions on Architecture and Code Optimization (TACO)**, Volume 2 Issue 4**Publisher:** ACM PressFull text available: [pdf\(565.90 KB\)](#) Additional Information: [full citation](#), [abstract](#), [references](#), [index terms](#)

This paper looks at the power-performance implications of running parallel applications on chip multiprocessors (CMPs). First, we develop an analytical model that, for the first time, puts together parallel efficiency, granularity of parallelism, and voltage/frequency scaling,

to establish a formal connection with the power consumption and performance of a parallel code running on a CMP. We then conduct detailed simulations of parallel applications running on a detailed power-performance CMP mod ...

Keywords: Voltage/frequency scaling, granularity, parallel efficiency

17 Compiler-directed channel allocation for saving power in on-chip networks



Guangyu Chen, Feihui Li, Mahmut Kandemir

January 2006 **ACM SIGPLAN Notices , Conference record of the 33rd ACM SIGPLAN-SIGACT symposium on Principles of programming languages POPL '06,**
Volume 41 Issue 1

Publisher: ACM Press

Full text available: pdf(943.11 KB) Additional Information: [full citation](#), [abstract](#), [references](#), [index terms](#)

Increasing complexity in the communication patterns of embedded applications parallelized over multiple processing units makes it difficult to continue using the traditional bus-based on-chip communication techniques. The main contribution of this paper is to demonstrate the importance of compiler technology in reducing power consumption of applications designed for emerging multi processor, NoC (Network-on-Chip) based embedded systems. Specifically, we propose and evaluate a compiler-directed a ...

Keywords: NoC, compiler, energy consumption

18 Power grid, thermal, and leakage issues: The need for a full-chip and package



thermal model for thermally optimized IC designs

Wei Huang, Eric Humenay, Kevin Skadron, Mircea R. Stan

August 2005 **Proceedings of the 2005 international symposium on Low power electronics and design ISLPED '05**

Publisher: ACM Press

Full text available: pdf(1.08 MB) Additional Information: [full citation](#), [abstract](#), [references](#), [index terms](#)

Modeling and analyzing detailed die temperature with a full-chip thermal model at early design stages is important to discover and avoid potential thermal hazards. However, omitting important aspects of *package* details in a thermal model can result in significant temperature estimation errors. In this paper, we discuss the applications of an existing compact thermal model that models both *die* and *package* temperature details. As an example, a thermally self-consistent leakage ...

Keywords: leakage, package, temperature-aware design, thermal model

19 Model and analysis for combined package and on-chip power grid simulation



Rajendran Panda, David Blaauw, Rajat Chaudhry, Vladimir Zolotov, Brian Young, Ravi Ramaraju

August 2000 **Proceedings of the 2000 international symposium on Low power electronics and design**

Publisher: ACM Press

Full text available: pdf(220.58 KB) Additional Information: [full citation](#), [abstract](#), [references](#), [citations](#), [index terms](#)

We present new modeling and simulation techniques to improve the accuracy and efficiency of transient analysis of large power distribution grids. These include an accurate model for the inherent decoupling capacitance of non-switching devices, as well as a statistical switching current model for the switching devices. Moreover, three new simulation techniques are presented for problem size-reduction and speed-up. Results of

application of these techniques on three PowerPCtm

20 On-chip communication architectures: analysis and optimisation: Power analysis of system-level on-chip communication architectures



Kanishka Lahiri, Anand Raghunathan

September 2004 **Proceedings of the 2nd IEEE/ACM/IFIP international conference on Hardware/software codesign and system synthesis**

Publisher: ACM Press

Full text available:  pdf(101.16 KB) Additional Information: [full citation](#), [abstract](#), [references](#), [index terms](#)

For complex System-on-chips (SoCs) fabricated in nanometer technologies, the system-level on-chip communication architecture is emerging as a significant source of power consumption. Managing and optimizing this important component of SoC power requires a detailed understanding of the characteristics of its power consumption. Various power estimation and low-power design techniques have been proposed for the global interconnects that form part of SoC communication architectures (e.g., low- ...

Keywords: communication architectures, low-power design, network-on-chip, power analysis, system-on-chip

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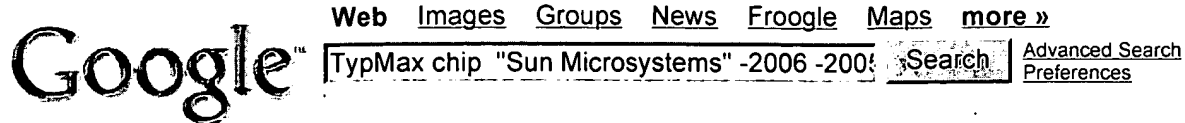
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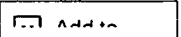

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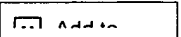

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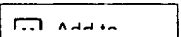
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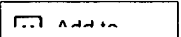
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